

A

B

C

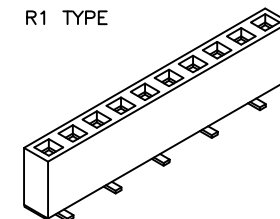
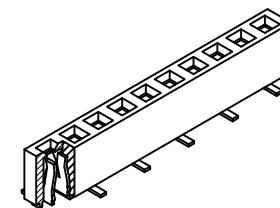
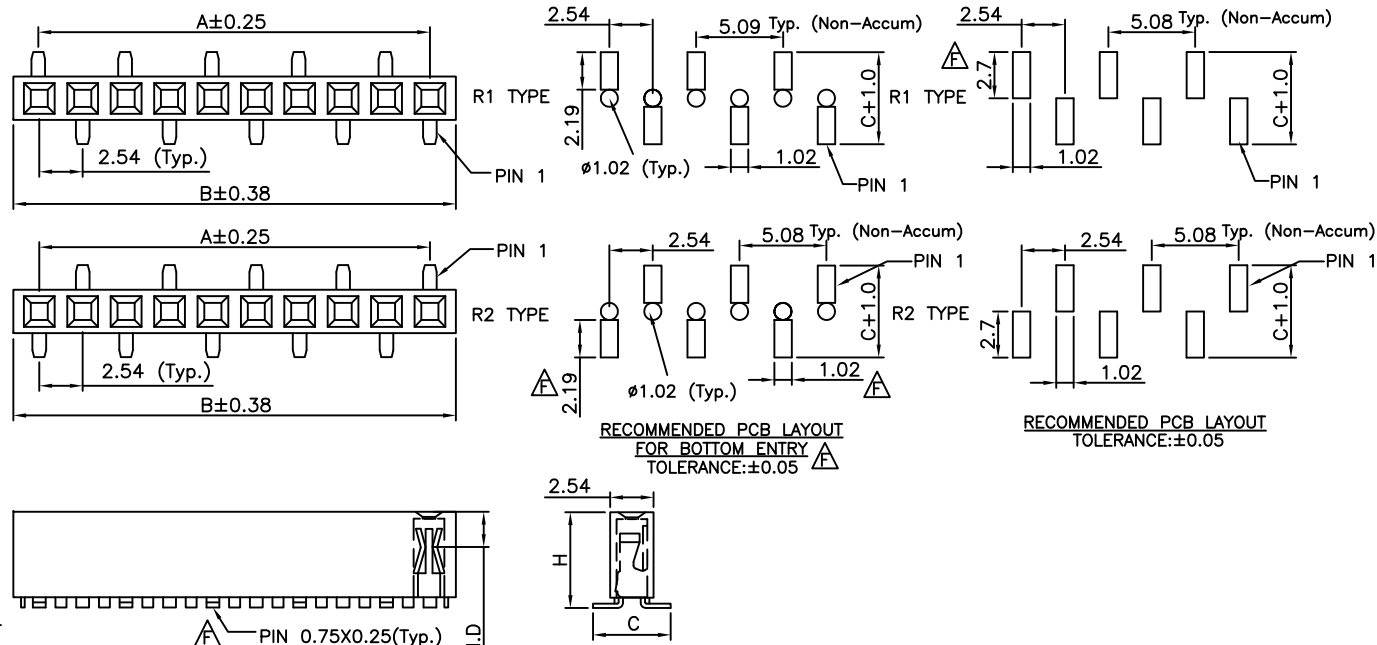
D

E

F

G

H



CONTACTS	DIMENSIONS	
	A	B
2	2.54	5.58
3	5.08	8.12
4	7.62	10.66
5	10.16	13.20
6	12.70	15.74
7	15.24	18.28
8	17.78	20.82
9	20.32	23.36
10	22.86	25.90
11	25.40	28.44
12	27.94	30.98
13	30.48	33.52
14	33.02	36.06
15	35.56	38.60
16	38.10	41.14
17	40.64	43.68
18	43.18	46.22
19	45.72	48.76
20	48.26	51.30
21	50.80	53.84
22	53.34	56.38
23	55.88	58.92
24	58.42	61.46
25	60.96	64.00
26	63.50	66.54
27	66.04	69.08
28	68.58	71.62
29	71.12	74.16
30	73.66	76.70
31	76.20	79.24
32	78.74	81.78
33	81.28	84.32
34	83.82	86.86
35	86.36	89.40
36	88.90	91.94
37	91.44	94.48
38	93.98	97.02
39	96.52	99.56
40	99.06	102.10

## SPECIFICATIONS 规格

CURRENT RATING 电流额定值: 3 AMP

INSULATOR RESISTANCE 绝缘电阻值: 1000 MEGOHMS MIN.

DIELECTRIC WITHSTANDING 耐电压: AC 600 V

CONTACT RESISTANCE 接触电阻值: 20mΩ Max.

OPERATING TEMPERATURE 工作温度: -40°C TO +105°C

CONTACT MATERIAL 端子物料: PHOSPHOR BRONZE

INSULATOR MATERIAL 绝缘体物料:

STANDARD 标准物料: POLYAMIDE 聚酰胺, NYLON 6T, UL 94-V0

OPTIONS 可选物料: POLYESTER 聚酯, LCP, UL 94-V0

SOLDERING PROCESS 可焊性:

NYLON 6T (STANDARD 标准物料) -

IR REFLOW 回流焊: 260°C for 10 sec.

WAVE 波峰焊: 230°C for 5-10 sec.

MANUAL SOLDER 人工焊接: 350°C for 3-5 sec

LCP (OPTION 可选物料) -

IR REFLOW 回流焊: 260°C for 10 sec.

WAVE 波峰焊: 250°C for 5-10 sec.

MANUAL SOLDER 人工焊接: 350°C for 3-5 sec

MATES WITH 配套之母座 (SUBJECT TO PIN LENGTH 在端子长度适合的条件下):

BG020 BG030 BG035 BG055 BG060

BG075 BG080

## Ordering Grid

BG125-XX-X-X-XXXX-X-X REQUEST SAMPLES &amp; QUOTATION

No. of Contacts  
02 to 40

## Contact Plating

A = Gold Flash All Over (Standard)

B = Selective Gold Flash Contact Area/

Tin On Tail

C = Tin All Over

G = 10μ" Gold Contact Area/Tin On Tail

I = 30μ" Gold Contact Area/Tin On Tail

Type  
1 = R1 Type  
2 = R2 TypeHeight H  
1 = 5.00mm (Standard)  
2 = 7.50mmInsulator Material  
N = Nylon 6T (Standard)  
L = LCPPacking Options  
C = Tape and Reel with Film (Standard)  
B = Tape and Reel with Cap  
D = Tube  
E = Tube with Cap  
F = Tube with FilmDimension C (Footprint Width) (1/100mm)  
'H' = 5.00mm: 0440 = 4.40mm (Standard)  
'H' = 7.50mm: 0420 = 4.20mm

For bottom entry applications, stringent soldering control &amp; pin alignment are required as lead to pad misalignment could cause incorrect mating.

By	LYH	PN	CB	ASE	SA	ASE	AJO
DETAIL	DRAWING RELEASE	ADDITION TO ORDER GRID	PACKING OPTIONS CHANGED	CORRECTION TO SPEC. & STD C DIM.	CORRECTION TO SPEC. & STD C DIM.	ADDITIONAL PCB LAYOUT ADDED	SELECTABLE WIDTH REMOVED
REV	A	B	C	D	E	F	G
DATE	30/10/06	09/03/09	27/04/09	04/08/09	23/06/10	25/05/12	25/06/12



Tolerances (Except as noted)		Part Number:-	Date:-
Dimensions in mm		BG125	30 OCT 06
Description:-		2.54mm PITCH SOCKET, SINGLE ROW, SURFACE MOUNT, VERTICAL, DUAL ENTRY	
X: $\pm 0.30$		X: $\pm 5^\circ$	
X.X: $\pm 0.25$		X.X: $\pm 3^\circ$	
X.XX: $\pm 0.15$		X.XX: $\pm 2^\circ$	
X.XXX: $\pm 0.10$		X.XXX: $\pm 1^\circ$	
Third Angle Projection		THIS DRAWING IS CONFIDENTIAL AND MUST NOT BE COPIED OR DISCLOSED WITHOUT WRITTEN CONSENT	
Scale	Revision	Material	Drawn by
NTS	G	See Note	LYH
Sheet No.		E & OE	
1/1			

GCT

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